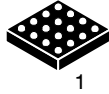


# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

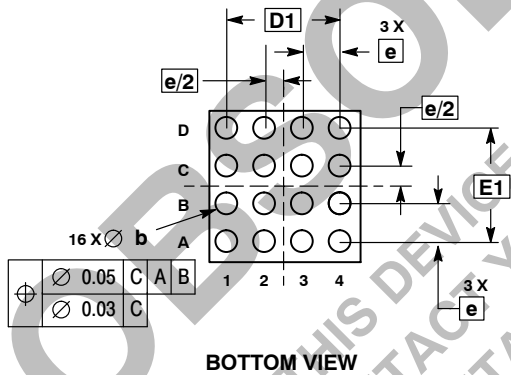
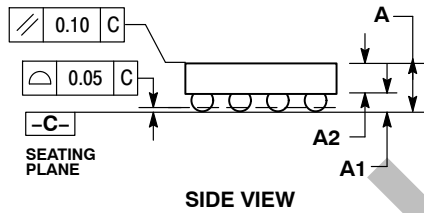
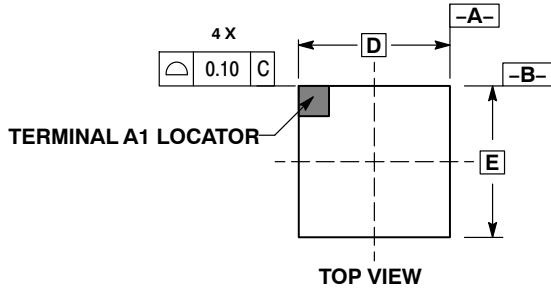
ON Semiconductor®



SCALE 4:1

16 PIN FLIP-CHIP  
CASE 499AR  
ISSUE B

DATE 17 DEC 2019



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

MILLIMETERS		
DIM	MIN	MAX
A	---	0.650
A1	0.210	0.270
A2	0.280	0.380
D	2.050 BSC	
E	2.050 BSC	
b	0.290	0.340
e	0.500 BSC	
D1	1.500 BSC	
E1	1.500 BSC	

THIS DEVICE IS OBSOLETE  
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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	16 PIN FLIP-CHIP, 2.05 X 2.05 MM	PAGE 1 OF 2

